

Product Change Notification - JAON-15IPCZ537

Date:

25 Sep 2019

Product Category:

Current And Power Measurement ICs; Closed Fan Controllers

Affected CPNs:



Notification subject:

CCB 3756 Final Notice: Qualification of NSEB as a new assembly site for selected SMSC EMC1701 and EMC2302 device families available in 10L MSOP (3x3mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for selected SMSC EMC1701 and EMC2302 device families available in 10L MSOP (3x3mm) package.

Pre Change:

Assembled at OSE using EN 4900G die attach, CEL-9200HF mold compound and C7025 lead frame material with Leadframe paddle size 81x90mils or 65x90 mils.

Post Change:

Assembled at NSEB using 8200T die attach, G600 mold compound and C7025 lead frame material with Leadframe paddle size 82x94 mils.

Pre and Post Change Summary:

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		hange	Post Change							
Assembly Site		niconductor nics, Ltd	UTAC Thai Limited (NSEB)							
	(03	SE)								
Wire material	А	.u	Au							
Die attach material	EN 4	900G	8200T							
Molding compound material	CEL-9200HF		G600							
Lead frame material	C7025		C7025							
Leadframe paddle size	81x90mils	65x90 mils	82x94 mils							

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying NSEB as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 25, 2019 (date code: 1943)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:



		March 2019					September 2019			October 2019					
Workweek	09	10	11	12	13	->	36	37	38	39	40	41	44	43	44
Initial PCN Issue Date					Χ										
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date														X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 28, 2019: Issued initial notification.

September 25, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on October 25, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-15IPCZ537_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

EMC1701-2-AIZL-TR

EMC2302-1-AIZL-TR

EMC2302-2-AIZL-TR

Date: Tuesday, September 24, 2019